features

- Power-On Reset Generator with Fixed Delay Time of 200 ms, no External Capacitor Needed
- Precision Supply Voltage Monitor 2.5 V, 3 V, 3.3 V, and 5 V
- Pin-For-Pin Compatible with the MAX705 through MAX708 Series
- Integrated Watchdog Timer (TPS3705 only)
- Voltage Monitor for Power-Fail or Low-Battery Warning
- Maximum Supply Current of 50 μA
- MSOP-8 and SO-8 Packages
- Temperature Range . . . −40°C to 85°C

typical applications

- Designs Using DSPs, Microcontrollers or Microprocessors
- Industrial Equipment
- Programmable Controls
- Automotive Systems
- Portable/Battery Powered Equipment
- Intelligent Instruments
- Wireless Communication Systems
- Notebook/Desktop Computers

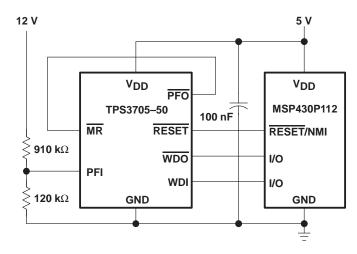
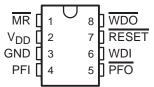
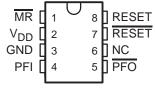


Figure 1. Typical MSP430 Application

TPS3705 . . . D PACKAGE (TOP VIEW)

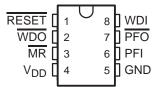


TPS3707 . . . D PACKAGE (TOP VIEW)

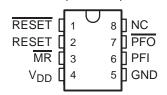


NC - No internal connection

TPS3705 . . . DGN PACKAGE (TOP VIEW)



TPS3707 . . . DGN PACKAGE (TOP VIEW)



NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



TPS3705-30, TPS3705-33, TPS3705-50 TPS3707-25, TPS3707-30, TPS3707-33, TPS3707-50 PROCESSOR SUPERVISORY CIRCUITS WITH POWER-FAIL

SLVS184B - NOVEMBER 1998 - REVISED JANUARY 1999

description

The TPS3705, TPS3707 family of microprocessor supply-voltage supervisors provide circuit initialization and timing supervision, primarily for DSP and processor-based systems.

During power-on, \overline{RESET} is asserted when the supply voltage V_{DD} becomes higher than 1.1 V. Thereafter, the supply voltage supervisor monitors V_{DD} and keeps \overline{RESET} active as long as V_{DD} remains below the threshold voltage V_{IT+} . An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time, t_{dtyp} = 200 ms, starts after V_{DD} has risen above the threshold voltage V_{IT+} . When the supply voltage drops below the threshold voltage V_{IT-} , the output becomes active (low) again. No external components are required. All the devices of this family have a fixed-sense threshold voltage V_{IT-} set by an internal voltage divider.

The TPS3705-xx and TPS3707-xx devices incorporate a manual reset input, \overline{MR} . A low level at \overline{MR} causes RESET to become active.

The TPS370x-xx families integrate a power-fail comparator which can be used for low-battery detection, power-fail warning, or for monitoring a power supply other than the main supply.

The TPS3705-xx devices have a watchdog timer that is periodically triggered by a positive or negative transition at WDI. When the supervising system fails to retrigger the watchdog circuit within the time-out interval, $t_{t(out)} = 1.6 \text{ s}$, \overline{WDO} becomes active. This event also reinitializes the watchdog timer. Leaving WDI unconnected disables the watchdog.

The TPS3707-xx devices do not have the Watchdog function, but include a high-level output RESET.

The product spectrum is designed for supply voltages of 2.5 V, 3 V, 3.3 V, and 5 V. The circuits are available in either 8-pin MSOP or standard SOIC packages. The TPS3705, TPS3707 devices are characterized for operation over a temperature range of –40°C to 85°C.

AVAILABLE OPTIONS

		PACKAGEI	D DEVICES		
TA	THRESHOLD VOLTAGE	SMALL OUTLINE (D)	POWER-PAD™ μ-SMALL OUTLINE (DGN)	MARKING DGN PACKAGE	CHIP FORM (Y)
	2.63 V	TPS3705-30D	TPS3705-30DGN	TIAAT	TPS3705-30Y
	2.93 V	TPS3705-33D	TPS3705-33DGN	TIAAU	TPS3705-33Y
	4.55 V	TPS3705-50D	TPS3705-50DGN	TIAAV	TPS3705-50Y
–40°C to 85°C	2.25 V	TPS3707-25D	TPS3707-25DGN	TIAAW	TPS3707-25Y
	2.63 V	TPS3707-30D	TPS3707-30DGN	TIAAX	TPS3707-30Y
	2.93 V	TPS3707-33D	TPS3707-33DGN	TIAAY	TPS3707-33Y
	4.55 V	TPS3707-50D	TPS3707-50DGN	TIAAZ	TPS3707-50Y



Function Tables

TRUTH TABLE, TPS3705

MR	V _{DD} >V _{IT}	RESET	TYPICAL DELAY
H→L	1	H→L	30 ns
L→H	1	L→H	200 ms
Н	1→0	H→L	3 μs
Н	0→1	L→H	200 ms

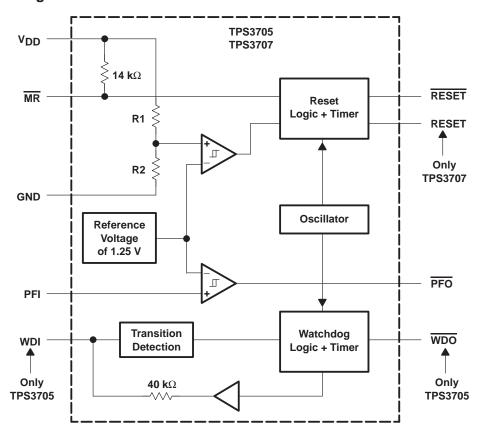
TRUTH TABLE, TPS3707

MR	V _{DD} >V _{IT}	RESET RESET		RESET RESET		TYPICAL DELAY
H→L	1	H→L	L→H	30 ns		
L→H	1	L→H	$H{ ightarrow}L$	200 ms		
Н	1→0	H→L	$L{\to}H$	3 μs		
Н	0→1	L→H	$H{ ightarrow} L$	200 ms		

TRUTH TABLE, TPS370x

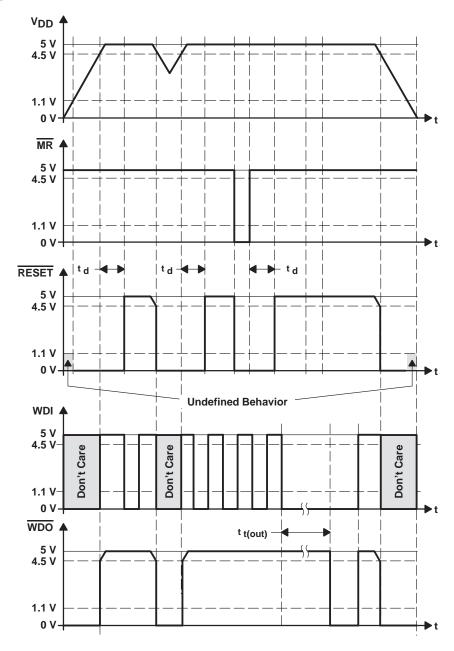
PFI>V _{IT}	PFO	TYPICAL DELAY
0→1	L→H	0.5 μs
1→0	H→L	0.5 μs

functional block diagram





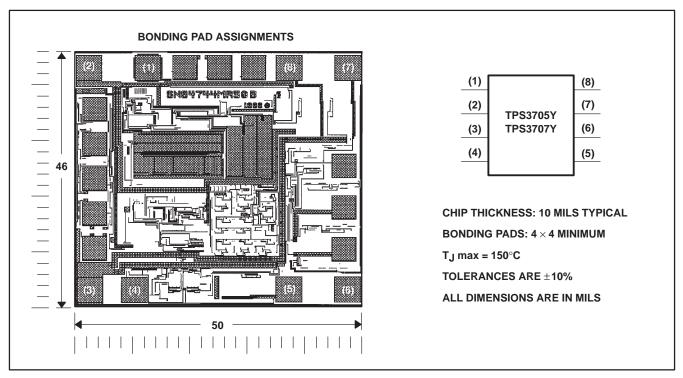
timing diagrams





TPS370xY chip information

These chips, when properly assembled, display characteristics similar to those of the TPS370x. Thermal compression or ultrasonic bonding may be caused on the doped-aluminum bonding pads. The chips may be mounted with conductive epoxy or a gold-silicon preform.



Terminal Functions

TERMINAL NAME				DESCRIPTION	
MR		1	ı	Manual reset	
VDD		2		Supply voltage	
GND		3		Ground	
PFI		4	ı	Power-fail comparator input	
PFO		5	0	Power-fail comparator output	
WDI	TPS3705	_	I	Watchdog timer input	
NC	TPS3707	6		No internal connection	
RESET		7	0	Active-low reset output	
WDO	TPS3705	8	0	Watchdog timer output	
RESET	TPS3707] °	0	Active-high reset output	

TPS3705-30, TPS3705-33, TPS3705-50 TPS3707-25, TPS3707-30, TPS3707-33, TPS3707-50 PROCESSOR SUPERVISORY CIRCUITS WITH POWER-FAIL

SLVS184B - NOVEMBER 1998 - REVISED JANUARY 1999

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V _{DD} (see Note1)	7 V
All other pins (see Note 1)	0.3 V to 7 V
Maximum low output current, I _{OL}	5 mA
Maximum high output current, IOH	
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{DD})	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	±20 mA
Continuous total power dissipation	. See Dissipation Rating Table
Operating free-air temperature range, T _A	–40°C to 85°C
Storage temperature range, T _{stq}	
Soldering temperature	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute—maximum—rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

	PACKAGE	T _A <25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
	DGN	2.14 W	17.1 mW/°C	1.37 W	1.11 W
ı	D	725 mW	5.8 mW/°C	464 mW	377 mW

recommended operating conditions at specified temperature range

	MIN	MAX	UNIT
Supply voltage, V _{DD}	2	6	V
Input voltage, V _I	0	V _{DD} +0.3	V
High-level input voltage, VIH	0.7×V _{DD}		V
Low-level input voltage, V _{IL}		0.3×V _{DD}	V
Input transition rise and fall rate at MR or WDI, Δt/ΔV		100	ns/V
Operating free-air temperature range, TA	-40	85	°C



NOTE 1: All voltage values are with respect to GND. For reliable operation the device must not be operated at 7 V for more than t = 1000h continuously.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT	
			TPS370x-xx	$V_{DD} = 1.1 \text{ V}$ $I_{OH} = -4 \mu A$	0.8				
			TPS3707-25	V V 0 0 V					
			TPS370x-30	V _{DD} = V _{IT+} + 0.2 V, I _{OH} = -500 μA	0.7×V _{DD}				
Vон	High-level output voltage		TPS370x-33	1011 000 p. 1				V	
			TPS370x-50	$V_{DD} = V_{IT+} + 0.2 \text{ V},$ $I_{OH} = -800 \mu\text{A}$	V _{DD} –1.5 V				
			TPS370x-xx	$V_{DD} = 6 \text{ V}, \qquad I_{OH} = -800 \mu\text{A}$	1				
			TPS370x-30	$V_{DD} = V_{IT+} + 0.2 \text{ V}, I_{OL} = 1 \text{ mA}$			0.3	V	
VOL	Low-level output voltage		TPS370x-33						
VOL.	Low lovel output voltage		TPS370x-50	$V_{DD} = V_{IT+} + 0.2 V,$ $I_{OL} = 2.5 \text{ mA}$			0.4	V	
			TPS370x-xx	$V_{DD} = 6 V$ $I_{OL} = 3 \text{ mA}$			0.4		
	Power-up reset voltage (see Note 2		2)	$V_{DD} \ge 1.1 \text{ V}, \qquad I_{OL} = 50 \mu\text{A}$			0.3	V	
			TPS3707-25		2.20	2.25	2.30		
			TPS370x-30	$T_A = 0$ °C to 85°C	2.57	2.63	2.68	V	
			TPS370x-33	1A = 0 C to 65 C	2.87	2.93	2.98		
	Negative-going input threshold voltage (see Note 3)		TPS370x-50		4.45	4.55	4.63		
V _{IT} _			TPS3707-25		2.20	2.25	2.32		
			TPS370x-30	T _A = -40°C to 85°C	2.57	2.63	2.70		
			TPS370x-33	1A = -40 C to 85 C	2.87	2.93	3.0		
			TPS370x-50		4.45	4.55	4.65		
		PFI	TPS370x-xx	$V_{DD} \ge 2 \text{ V}, \qquad T_A = -40^{\circ}\text{C to } 85^{\circ}\text{C}$	1.20	1.25	1.30	V	
			TPS3707-25			40			
		V _{DD}	TPS370x-30			50			
V _{hys}	Hysteresis	טט י	TPS370x-33			50		mV	
			TPS370x-50			70			
		PFI	TPS370x-xx			10			
I _{IH(AV)}	Average high-level input current	WDI		WDI = V_{DD} = 6 V, Time average (dc = 88%)		100	150	μΑ	
I _{IL(AV)}	Average low-level input current	VVDI		WDI = 0 V, $V_{DD} = 6 V$, Time average (dc = 12%)		-15	-20	μΑ	
	High lovel input current	WDI		WDI = V _{DD} = 6 V		120	170	^	
lін	High-level input current	MR		$\overline{MR} = 0.7 \times V_{DD}, V_{DD} = 6 V$		-130	-180	μΑ	
ļ	VE			$WDI = 0 V$, $V_{DD} = 6 V$		-120	-170	^	
ΙΙL	Low-level input current	MR		$\overline{MR} = 0 \text{ V}, \qquad \text{V}_{DD} = 6 \text{ V}$		-430	-600	μΑ	
Ц	Input current	PFI		$V_{DD} = 6 \text{ V}, \qquad 0 \text{ V} \leq V_{I} \leq V_{DD}$	-1	0	1	μΑ	
Inn	Supply current		TPS3707-xx	V _{DD} = 2 V to 6 V, MR = V _{DD} , MR, WDI and outputs unconnected		20	50	μΑ	
IDD	Supply current		TPS3705-xx	V _{DD} = 2 V to 6 V, MR= V _{DD} , MR, WDI and outputs unconnected		30	50	μΑ	
Ci	Input capacitance			$V_I = 0 V \text{ to } V_{DD}$		5		pF	

NOTES: 2. The lowest supply voltage at which RESET becomes active. t_{r,VDD} ≥ 15 μs/V
 3. To ensure best stability of the threshold voltage, a bypass capacitor (ceramic, 0.1 μF) should be placed near to the supply terminals.



TPS3705-30, TPS3705-33, TPS3705-50 TPS3707-25, TPS3707-30, TPS3707-33, TPS3707-50 PROCESSOR SUPERVISORY CIRCUITS WITH POWER-FAIL SLVS184B - NOVEMBER 1998 - REVISED JANUARY 1999

timing requirements at R $_L$ = 1 M $\Omega,$ C $_L$ = 50 pF, T $_A$ = 25 $^{\circ}C$

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT	
		at V _{DD}	$V_{DD} = V_{IT+} + 0.2 V,$	$V_{DD} = V_{IT} - 0.2 V$,	6			μs
t _w	Pulse width	at MR	$V_{DD} \ge V_{IT+} + 0.2 V$,	$V_{IL} = 0.3 \times V_{DD}$	$V_{IH} = 0.7 \times V_{DD}$	100			ns
		at WDI	$V_{DD} \ge V_{IT+} + 0.2 V$,	$V_{IL} = 0.3 \times V_{DD}$	$V_{IH} = 0.7 \times V_{DD}$	100			ns

switching characteristics at R_L = 1 M Ω , C_L = 50 pF, T_A = 25°C

	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _t (out)	Watchdog time out	V _{DD} ≥ V _{IT+} + 0.2 V, See timing diagram	1.1	1.6	2.3	s	
t _d Delay time			V _{DD} > V _{IT+} + 0.2 V, See timing diagram	140	200	280	ms
tPHL	Propagation (delay) time, high-to-low-level output	MR to RESET delay	$V_{DD} \ge V_{IT+} + 0.2 \text{ V},$		50	250	20
^t PLH	Propagation (delay) time, low-to-high-level output	MR to RESET delay (TPS3707–xx only)	$V_{IL} = 0.3 \times V_{DD}$ $V_{IH} = 0.7 \times V_{DD}$		50	250	ns
tPHL	Propagation (delay) time, high-to-low-level output	V _{DD} to RESET delay			3	5	
^t PLH	Propagation (delay) time, low-to-high-level output	V _{DD} to RESET delay (TPS3707-xx only)			3	5	μs
tPHL	Propagation (delay) time, high-to-low-level output	DELLA DEO dalam	V== 2.V to 6.V		0.5	1	
^t PLH	Propagation (delay) time, low-to-high-level output	PFI to PFO delay	V _{DD} = 2 V to 6 V		0.5	1	μs



TYPICAL CHARACTERISTICS

NORMALIZED INPUT THRESHOLD VOLTAGE

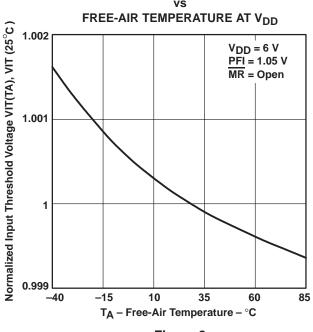
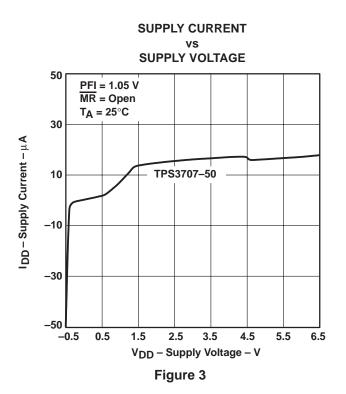
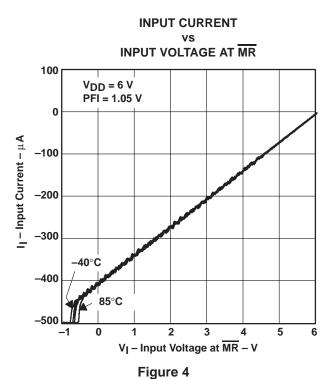


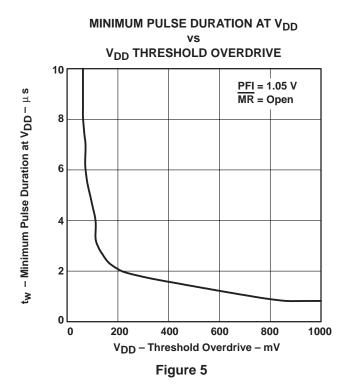
Figure 2

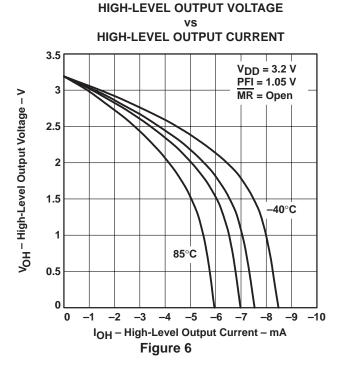


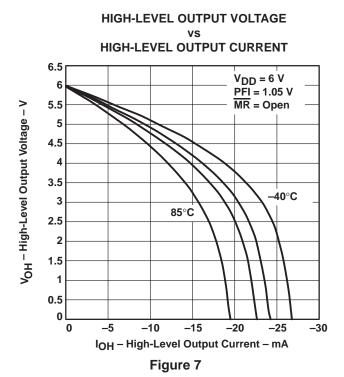


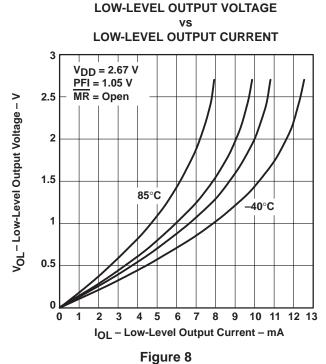
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TYPICAL CHARACTERISTICS







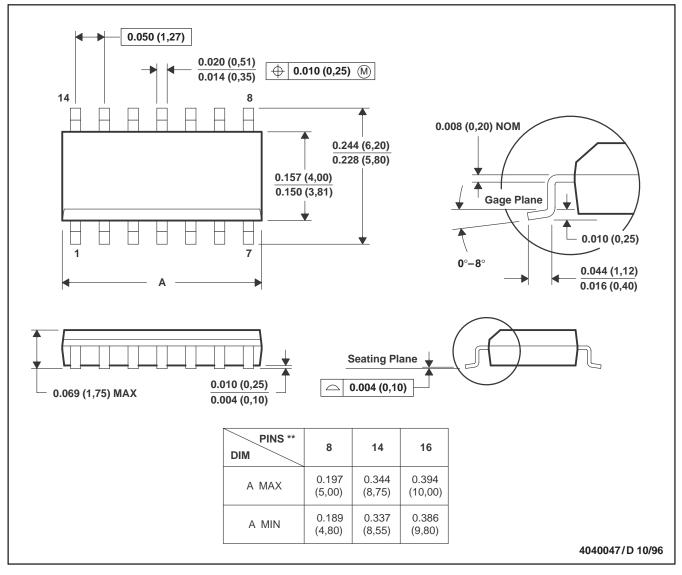


MECHANICAL DATA

D (R-PDSO-G**)

14 PIN SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

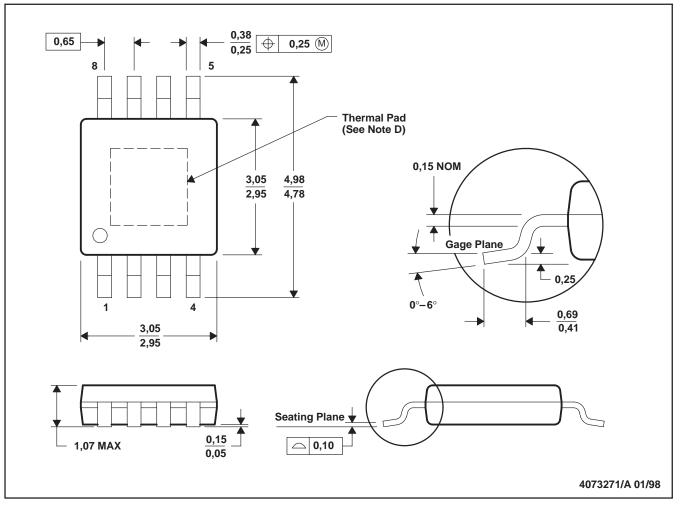
C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

MECHANICAL DATA

DGN (S-PDSO-G8)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions include mold flash or protrusions.
- D. The package thermal performance may be enhanced by attaching an external heat sink to the thermal pad. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
- E. Falls within JEDEC MO-187

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